

**8-PIN SOP, 400 V BREAK DOWN VOLTAGE NORMALLY CLOSE TYPE
2-ch Optical Coupled MOS FET****DESCRIPTION**

The PS7241-2B is a solid state relay containing GaAs LEDs on the light emitting side (input side) and normally close (N.C.) contact MOS FETs on the output side.

It is suitable for analog signal control because of their low offset and high linearity.

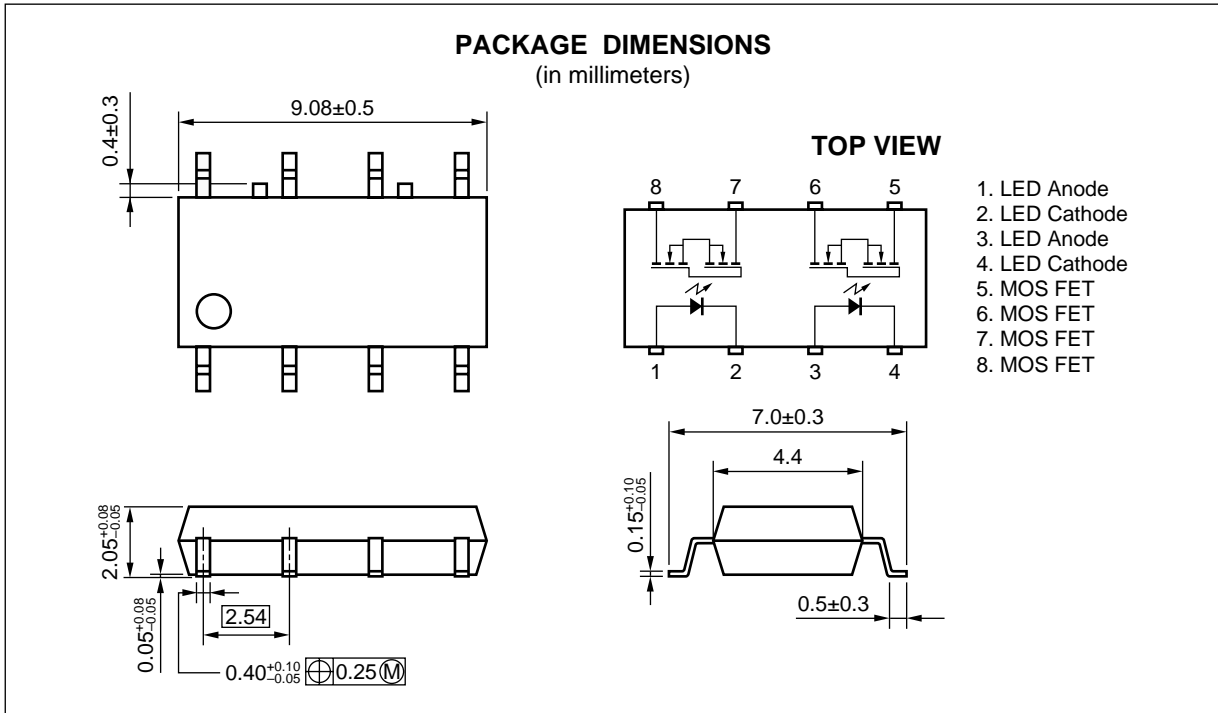
FEATURES

- 2 channel type (1 b + 1 b output)
- Low LED operating current ($I_f = 2 \text{ mA}$)
- Designed for AC/DC switching line changer
- Small and thin package (8-pin SOP, Height = 2.1 mm)
- Low offset voltage
- Ordering number of taping product: PS7241-2B-F3, F4
- UL approved: File No. E72422 (S)
- BSI approved: No. 8241/8242
- CSA approved: No. CA 101391

APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

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Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.



ORDERING INFORMATION

| Part Number | Package | Packing Style | Application Part Number ^{*1} |
|---------------|-----------|------------------------------|---------------------------------------|
| PS7241-2B | 8-pin SOP | Magazine case 45 pcs | PS7241-2B |
| PS7241-2B -F3 | | Embossed Tape 1 500 pcs/reel | |
| PS7241-2B -F4 | | | |

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

| Parameter | | Symbol | Ratings | Unit |
|---------------------------------|--|------------------|----------------|---------------|
| Diode | Forward Current (DC) | I _F | 50 | mA |
| | Reverse Voltage | V _R | 5 | V |
| | Power Dissipation | P _D | 50 | mW/ch |
| | Peak Forward Current ^{*1} | I _{FP} | 1 | A |
| MOS FET | Break Down Voltage | V _L | 400 | V |
| | Continuous Load Current | I _L | 120 | mA |
| | Pulse Load Current ^{*2} (AC/DC Connection) | I _{LP} | 200 | mA |
| | Power Dissipation | P _D | 180 | mW/ch |
| Isolation Voltage ^{*3} | | BV | 1 500 | Vr.m.s. |
| Total Power Dissipation | | P _T | 460 | mW |
| ★ | Operating Ambient Temperature | | T _A | -40 to +85 °C |
| Storage Temperature | | T _{stg} | -40 to +100 | °C |

*1 PW = 100 μs, Duty Cycle = 1 %

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output

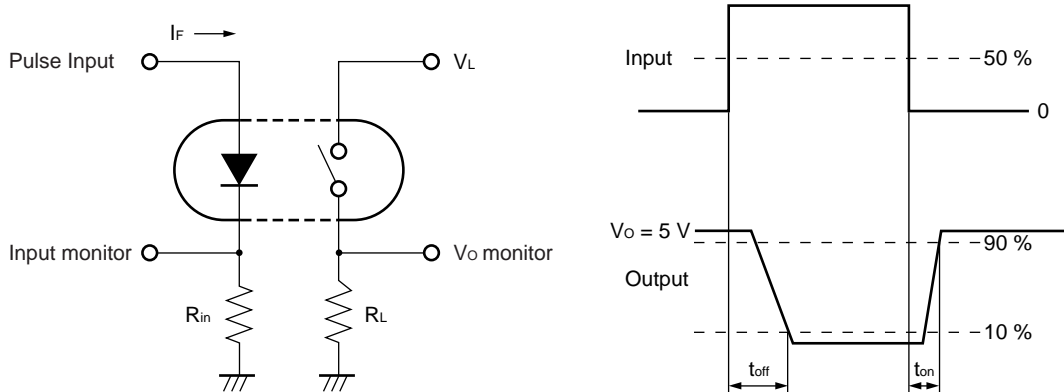
RECOMMENDED OPERATING CONDITIONS (T_A = 25 °C)

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|-----------------------|----------------|------|------|------|------|
| LED Operating Current | I _F | 2 | 10 | 20 | mA |
| LED Off Voltage | V _F | 0 | | 0.5 | V |

ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

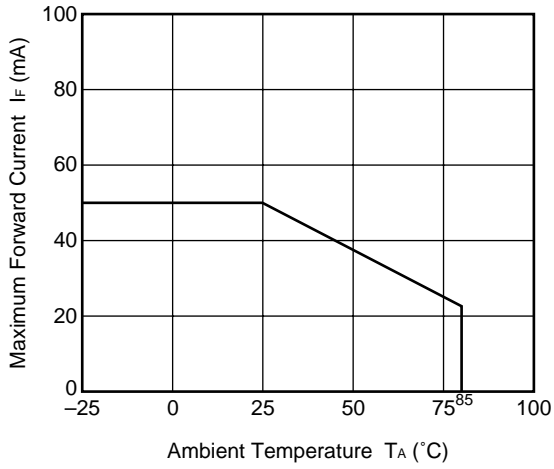
| Parameter | | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|-----------|-----------------------------|-------------------|---|-----------------|------|------|-------|
| Diode | Forward Voltage | V _F | I _F = 10 mA | | 1.2 | 1.4 | V |
| | Reverse Current | I _R | V _R = 5 V | | | 5 | μA |
| MOS FET | Off-state Leakage Current | I _{Loff} | I _F = 10 mA, V _D = 400 V | | 0.03 | 1.0 | μA |
| | Output Capacitance | C _{out} | I _F = 10 mA, V _D = 0 V, f = 1.0 MHz | | 185 | | pF/ch |
| Coupled | LED Off-state Current | I _{Foff} | I _L = 120 mA | | | 2.0 | mA |
| | On-state Resistance | R _{on1} | I _F = 0 mA, I _L = 10 mA | | 21 | 30 | Ω |
| | | R _{on2} | I _F = 0 mA, I _L = 120 mA, t ≤ 10 ms | | 16 | 25 | |
| | Turn-on Time ^{*1} | t _{on} | I _F = 10 mA, V _O = 5 V, R _L = 500 Ω, PW ≥ 10 ms | | 0.02 | 0.2 | ms |
| | Turn-off Time ^{*1} | t _{off} | | | 0.1 | 1.0 | |
| | Isolation Resistance | R _{I-O} | V _{I-O} = 1.0 kV _{DC} | 10 ⁹ | | | Ω |
| | Isolation Capacitance | C _{I-O} | V = 0 V, f = 1.0 MHz | | 0.4 | | pF/ch |

*1 Test Circuit for Switching Time

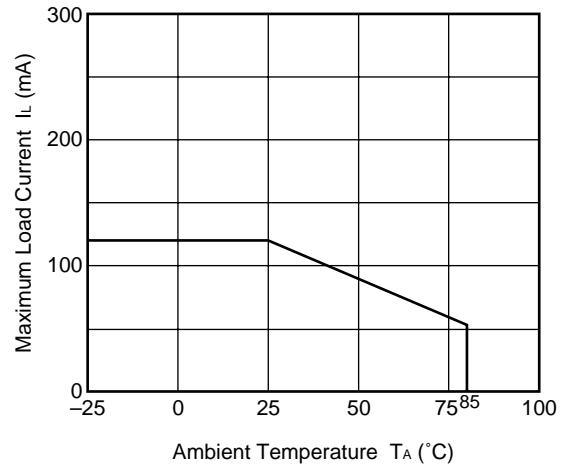


★ TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

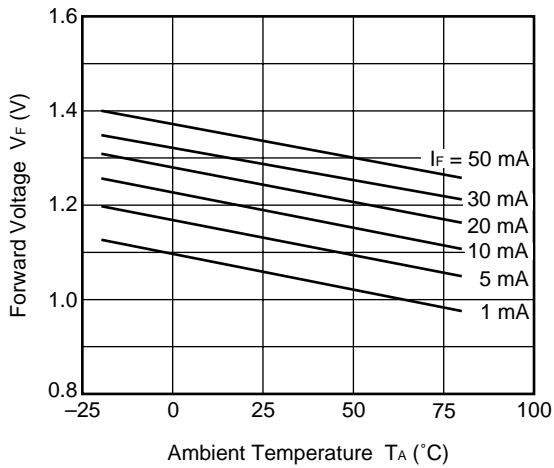
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



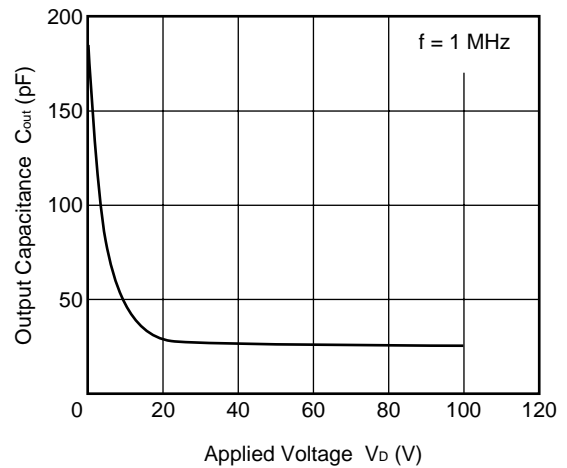
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



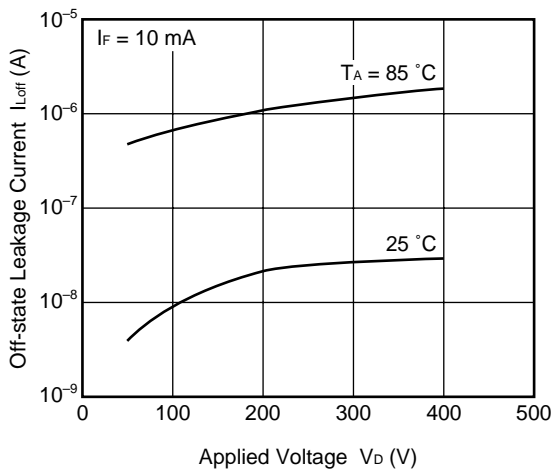
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



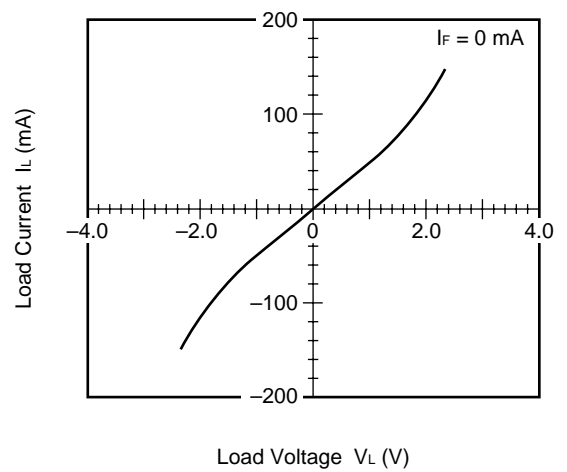
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



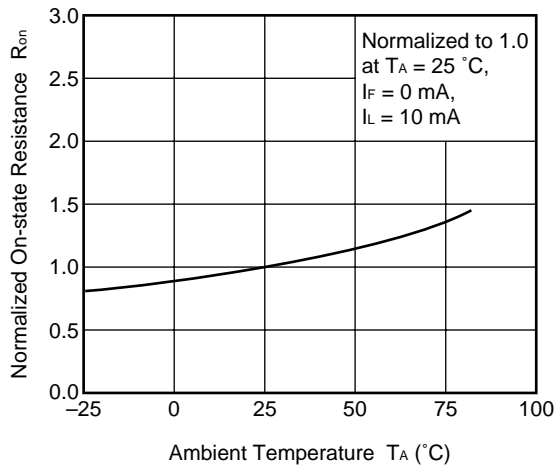
OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE



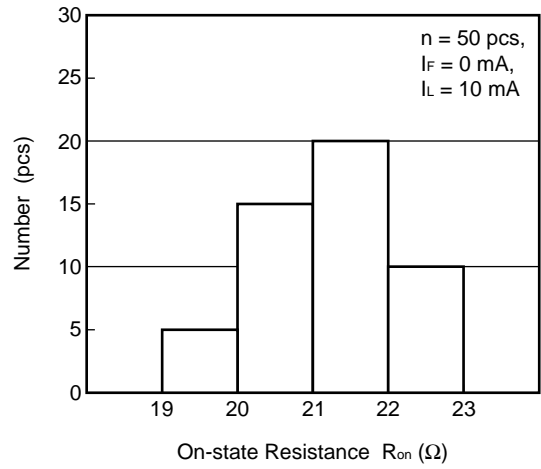
LOAD CURRENT vs. LOAD VOLTAGE



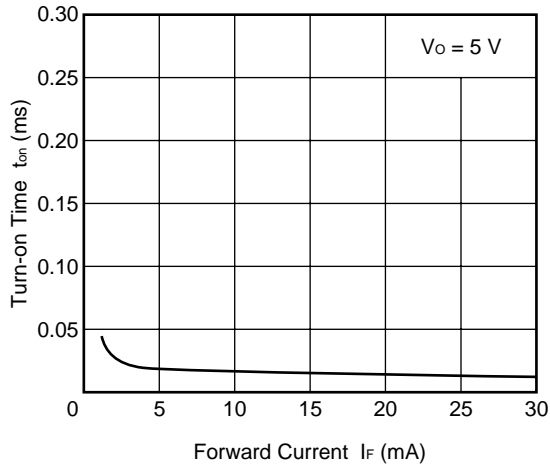
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



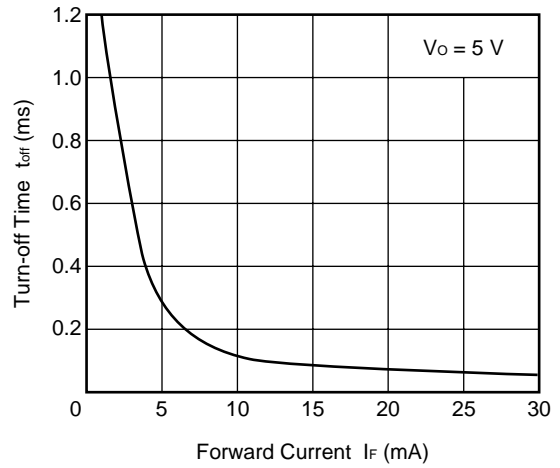
ON-STATE RESISTANCE DISTRIBUTION



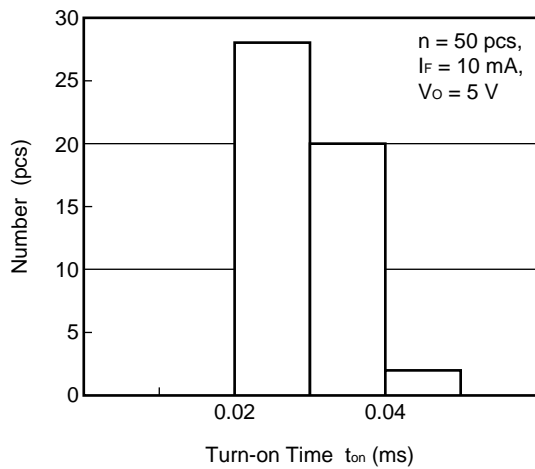
TURN-ON TIME vs. FORWARD CURRENT



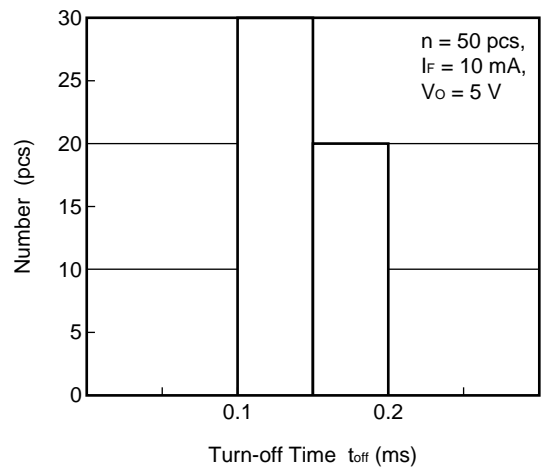
TURN-OFF TIME vs. FORWARD CURRENT



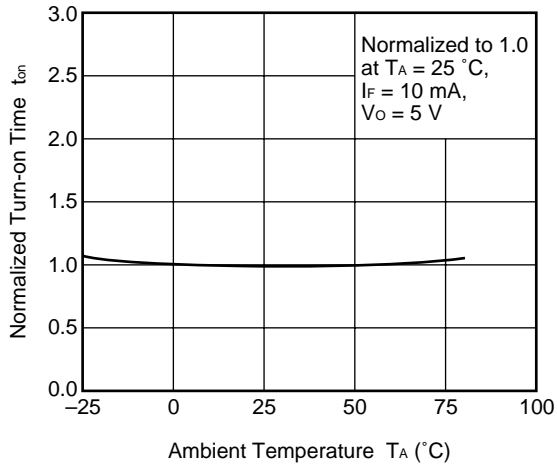
TURN-ON TIME DISTRIBUTION



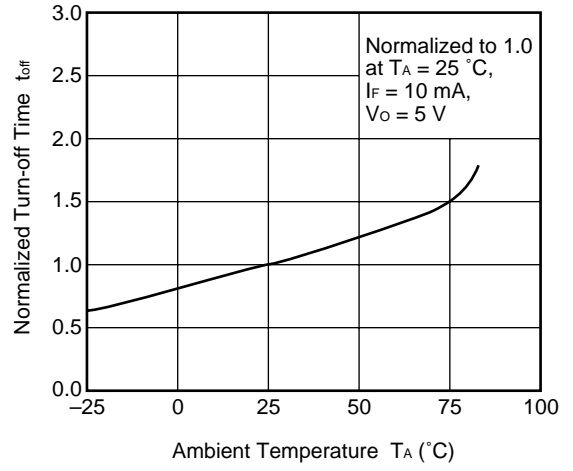
TURN-OFF TIME DISTRIBUTION



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



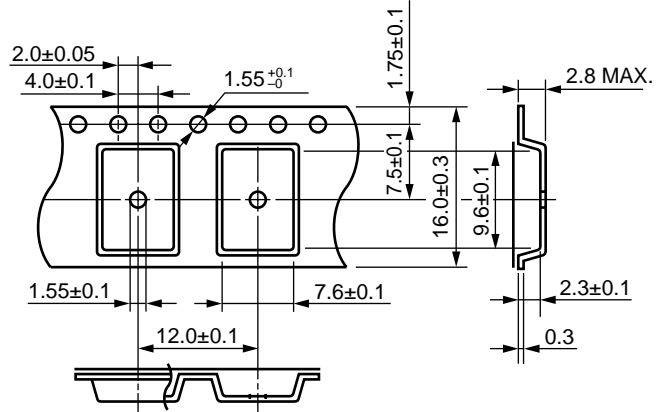
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



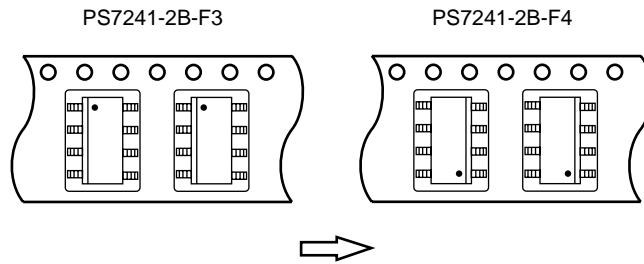
Remark The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (in millimeters)

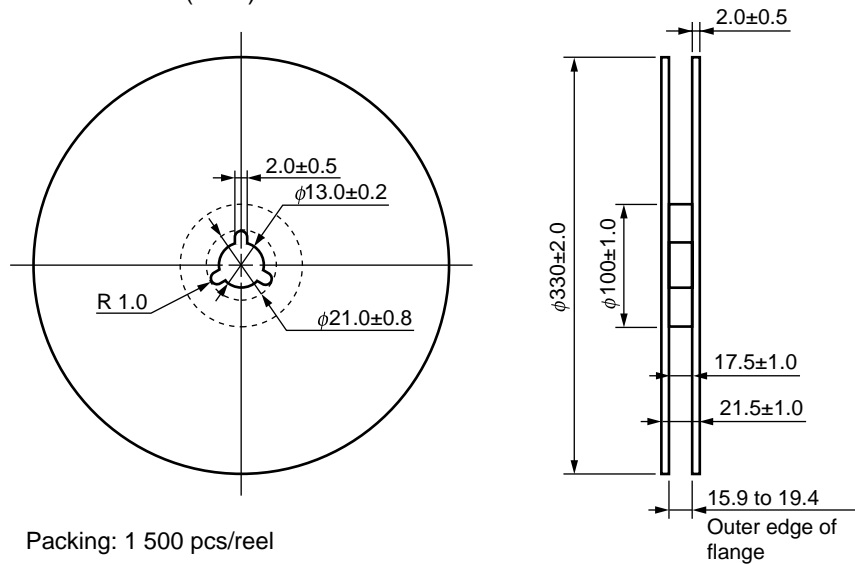
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



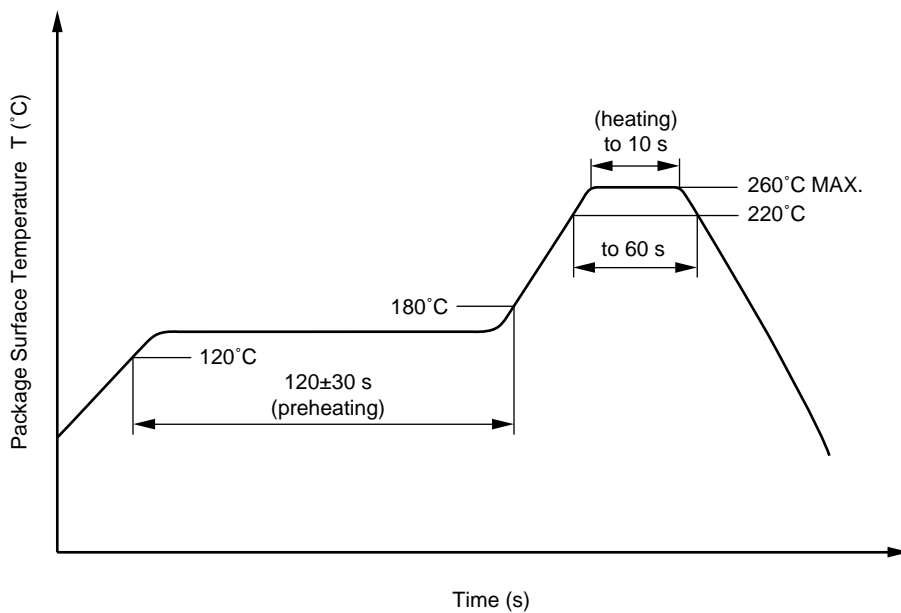
Packing: 1 500 pcs/reel

★ **RECOMMENDED SOLDERING CONDITIONS**

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Cautions

- Fluxes
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

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M8E 00.4-0110

SAFETY INFORMATION ON THIS PRODUCT

| | | |
|-----------------------|----------------------|---|
| <p>Caution</p> | <p>GaAs Products</p> | <p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p> |
|-----------------------|----------------------|---|

► For further information, please contact

NEC Compound Semiconductor Devices, Ltd.

5th Sales Group, Sales Division TEL: +81-44-435-1588 FAX: +81-44-435-1579 E-mail: salesinfo@csd-nec.com

NEC Compound Semiconductor Devices Hong Kong Limited

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
 Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
 Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH <http://www.ee.nec.de/>

TEL: +49-211-6503-01 FAX: +49-211-6503-487

California Eastern Laboratories, Inc. <http://www.cel.com/>

TEL: +1-408-988-3500 FAX: +1-408-988-0279

Identification of Lead-Free Products

Part Number

The product type is indicated by a code suffixed to the part number.

| Type of lead-free product | Identification code | Comment |
|---------------------------|---------------------|---|
| Totally lead free | -A | Product contains no lead in any area |
| | -AX | Product has Ni/Pd/Au plating on external pins |
| Partially lead free | -AZ | Product contains lead in some areas |

Product Marking

- A dot "." is used as the lead free mark.
- The lead free identification codes -A, -AX, and -AZ do not appear in the product marking.

Marking example

Marking example

Identification on Packing Label

Both totally lead-free products and partially lead-free products include the indication "Pb-Free T." on the packing label.



Example of Label Indication

Example of Label Indication
